Bryan Black received his Ph.D. in Electrical and Computer Engineering from Carnegie Mellon. With almost 30 years of experience, Black has had the honor of working at Motorola, Intel, and AMD. He has done a little of everything from devices to circuits to microarchitecture to DRAM to packaging, test, and manufacturing. Currently Black is a Senior AMD Fellow responsible for AMD advanced graphics memory systems and packaging solutions. In 2015 AMD introduced its first die stacked products integrating High Bandwidth Memory (HBM) on an interposer, the AMD Radeon™ R9 Fury family of graphics products, making Black the creator of HBM and a leader in Die Stacking in the industry. This work laid the technology foundation of the AI industry as we know it today.